

Approved by:

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SPECIFICATION

MODEL:D901

SURFACE ACOUSTIC WAVE DUPLEXER

CAUTION: ELECTROSTATIC SENSITIVE DEVICE(ESD)

Observe precautions for handling

Package Type: QCC8

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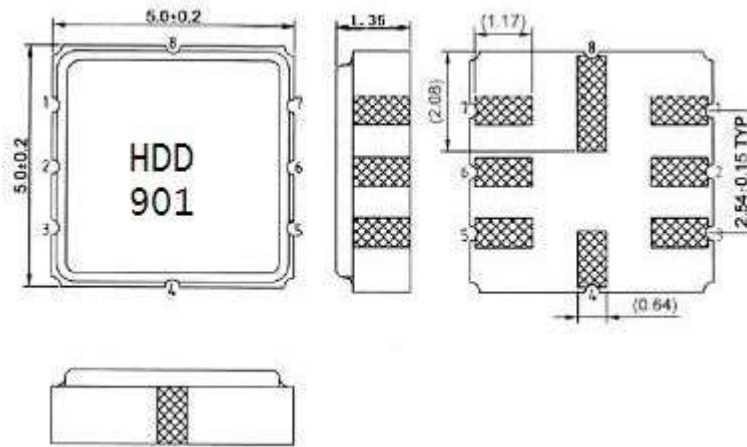
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1. OUTLINE DRAWING AND DIMENSION

Ceramic package QCC8 (Unit:mm)



tolerance: ± 0.1

2. MARKING

HDD
901

Pin configuration	
6.	Ant
1.	Tx (926.25)
3.	Rx (903.75)
5.7.	Ant ground
2.	Rx ground
4.8.	Case/tx ground

① Logo: HD

② Model No. : D901

3. PERFORMANCE

3-1. APPLICATION

SAW Duplexer for Cordless Telephone

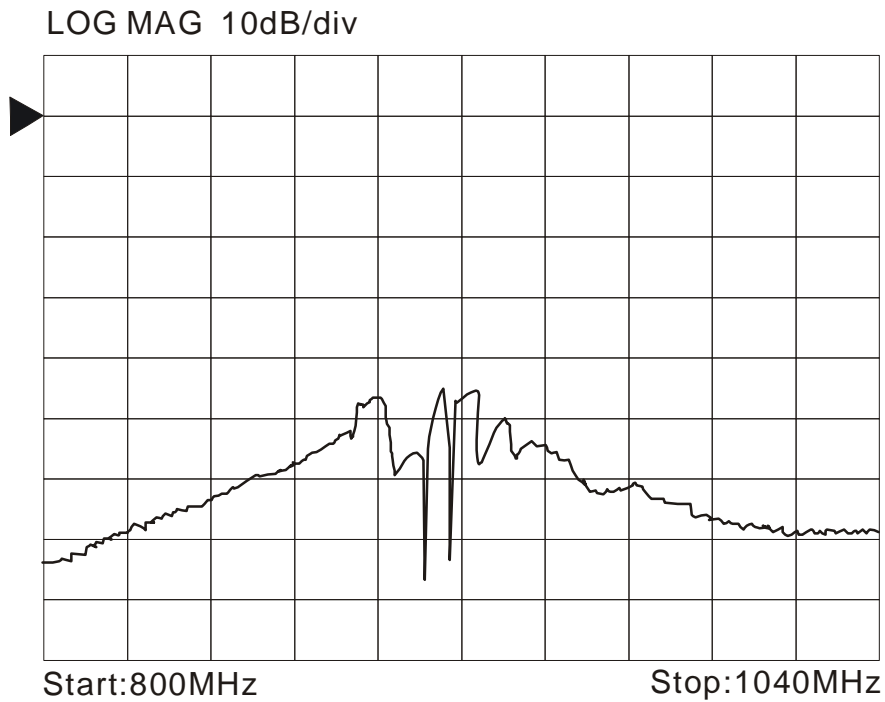
Center Frequency Tx(f_T): 926.25MHz

Center Frequency Rx(f_R): 903.75MHz

3-2. MAXIMUM RATING

CHARACTERISTICS	RATING	UNITS
DC Permissive Voltage	0	V
Maximum Input Power	5	dBm
Operating Temperature Range	-20 ~ +60	$^{\circ}\text{C}$
Storage Temperature Range	-40 ~ +85	$^{\circ}\text{C}$

③ Frequency response (Tx→Rx)



4. RELIABILITY

4-1. LIFE TEST

ITEM	TEST CONDITION	LIMIT
High Temperature Exposure Low Temperature Exposure Moisture Resistance	Ta = + 85 ± 2°C, 100H Ta = -30 ± 2°C, 100H Ta = + 40 ± 2°C, RH 95%, 120H	After the test, specimen would be kept at room temperature for 2 hours. Specimen shall meet the electrical specification.

4-2. HEAT CYCLE, SOLDERING TEST

ITEM	TEST CONDITION	LIMIT
Temperature Cycle	-20°C, 30min ←→ +110°C, 30min 10 cycle	Same as 4-1
Solder ability	Immerse in soldering bath at 230 ± 5°C, 5 ± 1sec.	More than 3/4 area If the soldering pad must be covered with new solder.
Resistance to Soldering Heat (Reflow)	Preheat: 180°C, 2min. Reflow: 240°C, 10sec.	Same as 4-1

4-3. MECHANICAL TEST

ITEM	TEST CONDITION	LIMIT
Vibration	Amplitude=1.5mm,10 ← → 55Hz,sweep time=1min,3direction each 2H	Same as 4 -1
Shock	Peak acceleration=1500G,durati on=0.5msec,wave form=half-sin, 6 direction each 3 shocks.	

5. CAUTION

- 5-1. This is an electrostatic sensitive device. Please avoid static voltage during operation and storage.
- 5-2. Sudden change of temperature shall be avoided ,deterioration If the characteristics can occur.
- 5-3. Ultrasonic vibration may cause deterioration and destruction of the components Please avoid ultrasonic cleaning.

7. Packing

7.1 Dimensions

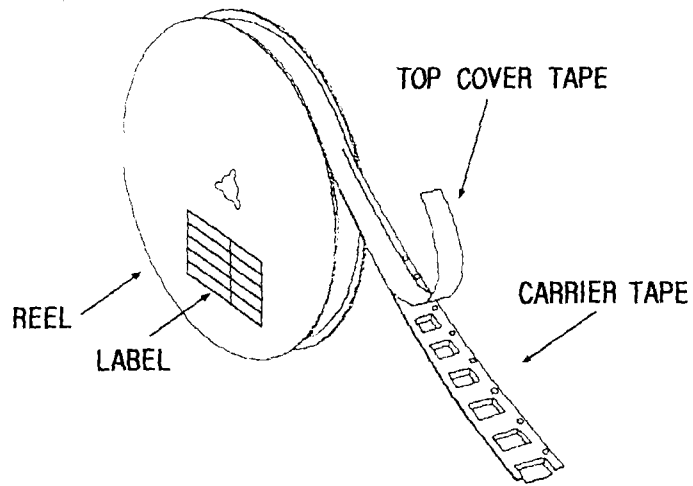
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity

- 1000 pcs/reel 7"
- 3000 pcs/reel 13"

7.3 Taping Structure

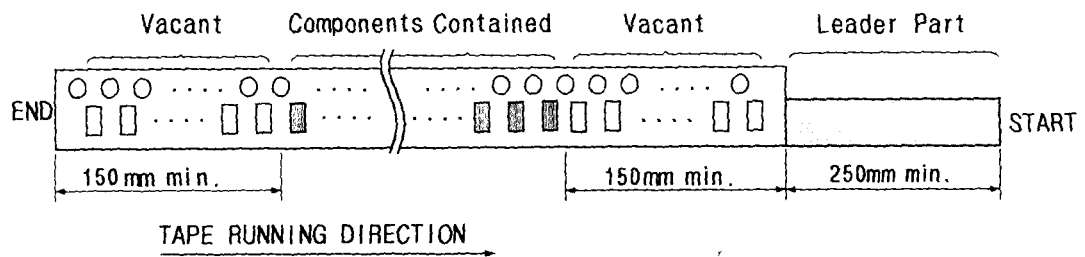
- (1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



8. TAPE SPECIFICATIONS

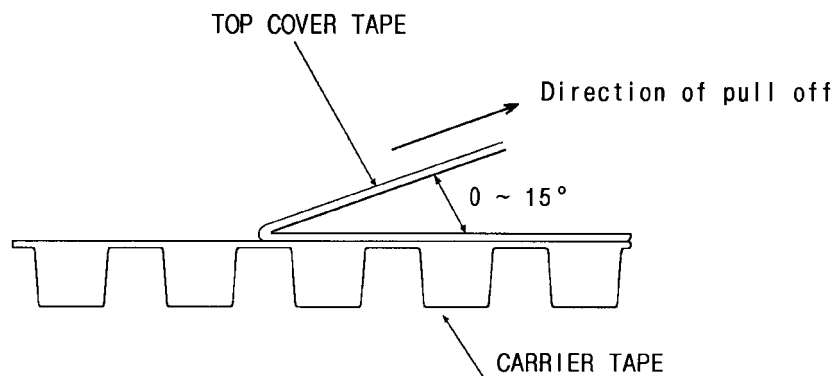
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

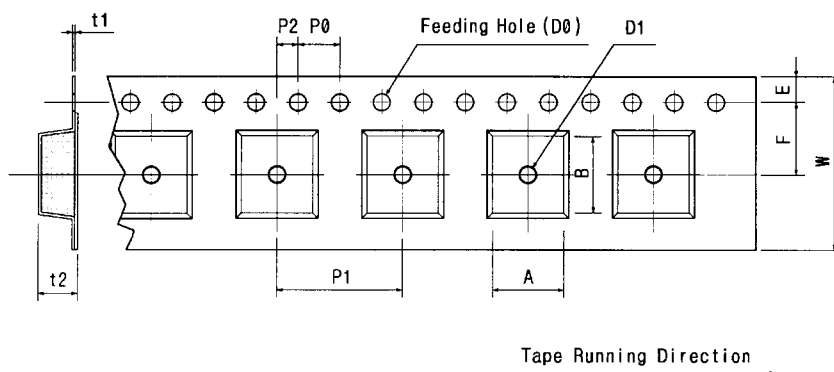
(1) pull off angle: 0~15°

(2) speed: 300mm/min.

(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

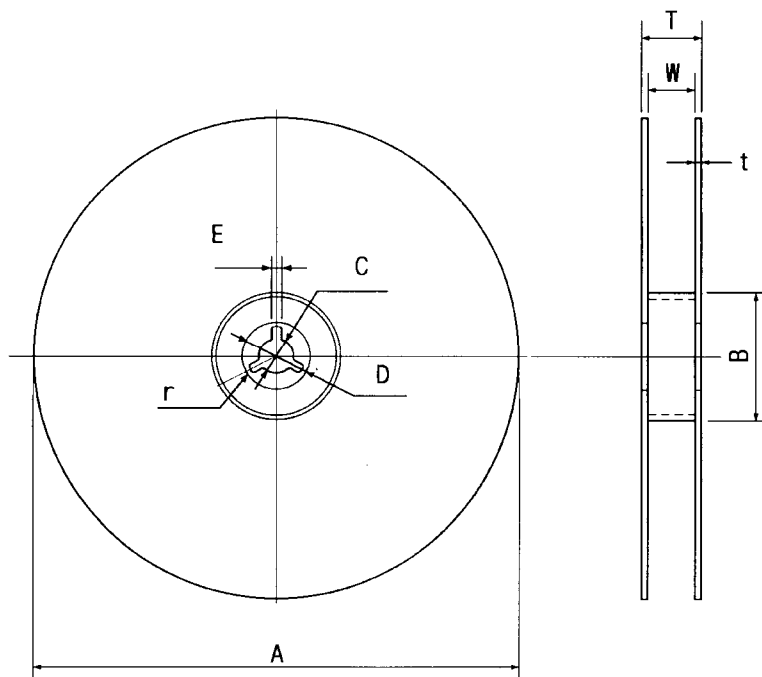


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0	5.5	1.75	4.0	8.0	2.0	Ø1.5	Ø1.0	0.3	2.10	6.40	5.20
±0.3	±0.05	±0.1	±0.1	±0.1	±0.05	±0.1	±0.25	±0.05	±0.1	±0.1	±0.1

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	13	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.